

# 2SK3844-VB Datasheet N-Channel 60 V (D-S) MOSFET

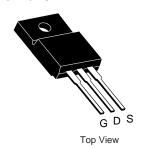
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>		
60	0.005 at V <sub>GS</sub> = 10 V	120		
00	0.013 at V <sub>GS</sub> = 4.5 V	95		

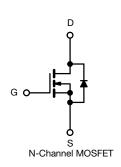
### **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:



### **TO-220 FULLPAK**





Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
Continuous Dunin Courset /T 475 90\b	T <sub>C</sub> = 25 °C	l <sub>D</sub>	120	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C		95 <sup>a</sup>	Δ
Pulsed Drain Current	<u>.</u>	I <sub>DM</sub>	300	А
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	70 <sup>a</sup>	
Avalanche Current		I <sub>AS</sub>	50	1
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Maximum Dawar Dissination	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	VV
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marianura lunation to Ambianta	t ≤ 10 sec	R <sub>thJA</sub>	15	18	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	¹`thJA	40	50	°C/W
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1	

### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$

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Parameter	Symbol	Test Conditions	Min.	Typ.a	Max.	Unit
Static	Oymbor	rest conditions	141111	тур.	mux.	Ome
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	60			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1	2	3	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		<del>                                     </del>	± 100	nA
	000	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$		1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA
<u> </u>		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	=
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α
	(* /	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.005		
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.010		Ω \$
rain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.015	Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.013		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S
Dynamic			L			
Input Capacitance	C <sub>iss</sub>			5650		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1120		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			525		
Total Gate Charge <sup>c</sup>	Qg			47	70	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		10		nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_L = 0.6 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	25	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			35	50	- ns
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)				
Pulsed Current	I <sub>SM</sub>			300		Α
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns

### Notes:

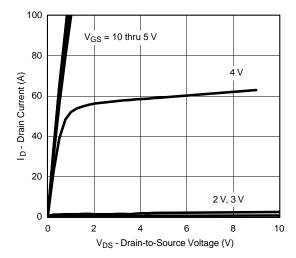
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

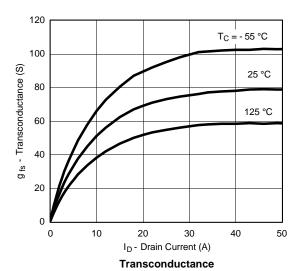
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### TYPICAL CHARACTERISTICS (25 °C unless noted)



### **Output Characteristics**

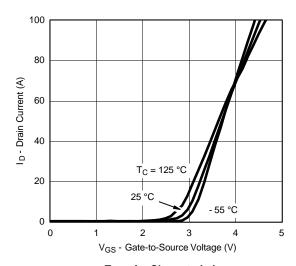


### 7000 6000 $C_{\text{iss}}$ C - Capacitance (pF) 5000 4000 3000 2000 $\mathsf{C}_{\mathsf{oss}}$ 1000 $\mathsf{C}_{\mathsf{rss}}$ 0 0 10 20 30 50 60

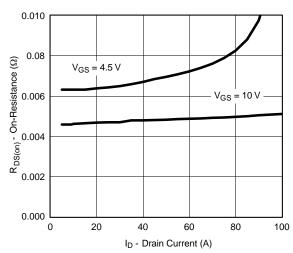
V<sub>DS</sub> - Drain-to-Source Voltage (V)

Capacitance

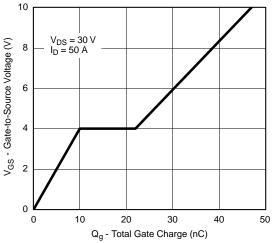
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### **Transfer Characteristics**



**On-Resistance vs. Drain Current** 

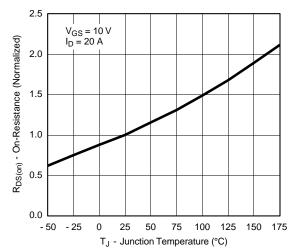


**Gate Charge** 

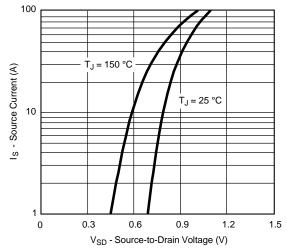
8000



### TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

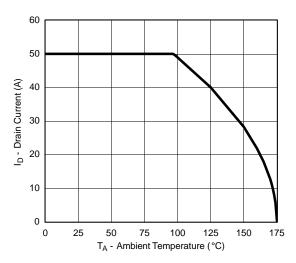


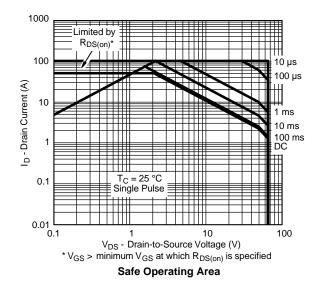
Source-Drain Diode Forward Voltage

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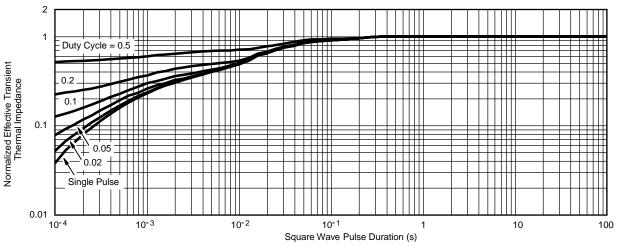


### THERMAL RATINGS





**Maximum Drain Current vs. Ambient Temperature** 



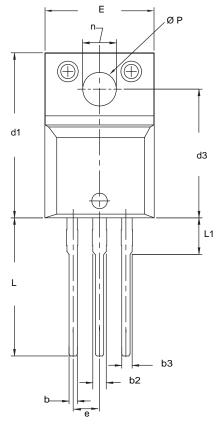
Normalized Thermal Transient Impedance, Junction-to-Case

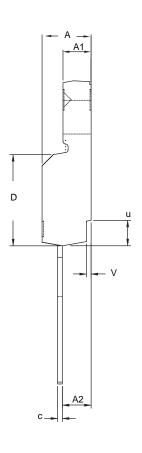
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### **TO-220 FULLPAK (HIGH VOLTAGE)**





DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54	BSC	0.100	BSC
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØΡ	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

ECN: X09-0 DWG: 5972

- To be used only for process drawing.
  These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
  All critical dimensions should C meet C<sub>pk</sub> > 1.33.
  All dimensions include burrs and plating thickness.
  No chipping or package damage.

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